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Lake to Atkins-Olson Memorial Park -- 20 Bark River B: Rome Dam to Hebron -- 21 Bark River C: Koch Road to Burnt Village Park -- 22 Illinois Fox River: County Road H to County Road ES -- 23 Koshkonong Creek: Cambridge to Hoopen Road -- 24 Mukwonago River: County Road LO to County Road I -- 25 Pewaukee River and Illinois Fox River: Pewaukee to Waukesha -- 26 Red Cedar Lake State Natural Area: Cambridge in Jefferson County.
27 Sugar River C: Avon Bottoms to Yale Bridge Road in Illinois -- 28 Turtle Creek A: Fairfield Area in Walworth and Rock Counties -- 29 Turtle Creek B: South O'Riley Road to Sweet-Allyn Park -- 30 Turtle Creek C: Sweet-Allyn Park to Dickop Street in Illinois -- 31 White River (Walworth County): Sheridan Springs Road to Burlington -- 32 Yahara River B: Dunkirk Dam to Rock River -- Part Three Southwest of Madison -- 33 Governor Dodge State Park: Cox Hollow and Twin Valley Lakes -- 34 Little Platte River: Quarry Road to County Road O -- 35 Little Sugar River: Schneeberger Road to Albany -- 36 Pecatonica River A: County Road O to Darlington -- 37 Pecatonica River B: Roller Coaster Road to Walnut Road -- 38 Pecatonica River East Branch A: Hollandale to Blanchardville -- 39 Pecatonica River East Branch B: Blanchardville to Argyle -- 40 Pecatonica River East Branch C: Argyle to Blackhawk Memorial Park -- 41 Platte River: Platte Road to Big Platte Road -- 42 Sugar River A: Verona to Paoli in Dane County -- 43 Sugar River B: Brodhead Dam to Avon Bottoms -- Part Four Northwest of Madison -- 44 Baraboo River A: Wonewoc to La Valle -- 45 Baraboo River B: La Valle to Lake Redstone -- 46 Baraboo River C: Rock Springs to North Freedom -- 47 Baraboo River D: Baraboo Rapids -- 48 Black Earth Creek: Olson Road to Lions Park -- 49 Dell Creek and Mirror Lake: Dellwood and Lake Delton in Sauk County -- 50 Devil's Lake State Park: Baraboo in Sauk County -- 51 Lemonweir River: Mauston Dam to Two Rivers Boat Landing -- 52 Neenah Creek A: Chauncey Street to County Road A -- 53 Neenah Creek B: County Road P to Muskrat Road -- 54 Neenah Creek C: Muskrat Road to County Road CX -- 55 Pine River A: Pier Natural Bridge Park to County Road AA -- 56 Pine River B: County Road AA to Bohmann Drive -- 57 Pine River C: Twin Bluffs Drive to Wisconsin River.
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Sommario/riassunto

South-central Wisconsin provides an impressive array of opportunities for all types of paddling, including some of the very best day trips in the entire state and even Upper Midwest. Paddling South Central Wisconsin, by experienced paddler and author Timothy Bauer, guides all types of paddlers, whether veteran or novice, through whitewater adrenaline or flatwater calm routes near Madison, Rockford, Janesville, Waukesha, and Milwaukee. This paddling guide is the perfect companion for those seeking "the rowed less taken." It describes the best times to paddle 60 diverse routes, alerts readers to each paddle's difficulty level and estimated length, and suggests side trips, optional trip extensions, and alternate routes to paddle, depending on weather conditions. Easy-to-follow maps, complete with GPS coordinates and driving directions, add to this book's high value. In addition, the author

provides contact information on local paddling clubs, outfitters, and Internet links.

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Sommario/riassunto

"Electrostatic discharge (ESD) is the sudden and momentary electric current that flows when an excess of electric charge, stored on an electrically insulated object, finds a path to an object at a different electrical potential (such as the earth). In the electronics industry, a failure mechanism describes momentary unwanted currents that may cause damage to electronic equipment. This can clearly be very costly, and it is advantageous to find ways of preventing this discharge, or to limit its damage when it does occur. ElectroStatic Discharge (ESD) is a common problem in the semiconductor environment. This book discusses ESD protection, filling a gap in the market as currently there is no ?ESD Handbook? for the semiconductor industry".